

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

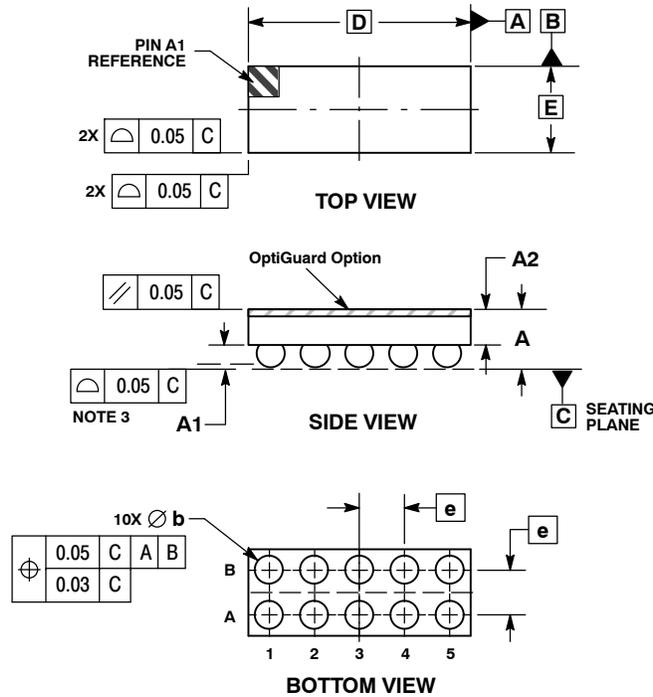
ON Semiconductor®



SCALE 4:1

**WLCSP10, 2.46x0.96**  
CASE 567BG-01  
ISSUE O

DATE 26 JUL 2010

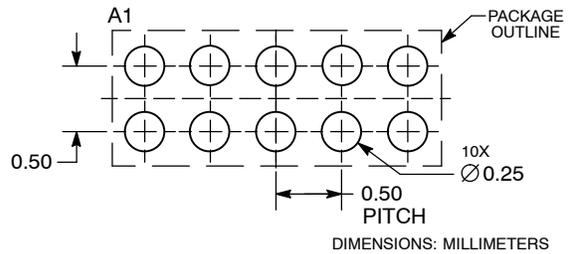


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.56	0.72
A1	0.21	0.27
A2	0.42 REF	
b	0.29	0.35
D	2.46 BSC	
E	0.96 BSC	
e	0.50 BSC	

**RECOMMENDED SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>STATUS:</b>	<b>ON SEMICONDUCTOR STANDARD</b>	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	<b>WLCSP10, 2.46X0.96</b>	<b>PAGE 1 OF 2</b>

